

## **The mechanism of mobility degradation in MISFETs with Al<sub>2</sub>O<sub>3</sub> gate dielectric**

K. Torii, Y. Shimamoto, S. Saito, O. Tonomura, M. Hiratani, \*Y. Manabe, \*M. Caymax, \*\*J. W. Maes

Central Research Laboratory, Hitachi Ltd., Kokubunji, Tokyo 185-8601, Japan

\*IMEC, Kapeldreef 75, B-3001 Leuven, Belgium

\*\*ASM international NV, Bilthoven, The Netherlands

We fabricated FETs with ALCVD-Al<sub>2</sub>O<sub>3</sub> gate dielectric and examined the effect of surface treatment before Al<sub>2</sub>O<sub>3</sub> deposition. Pre-nitridation is effective to reduce flat band shift and gate depletion. By optimizing the post-oxidation and controlling the interfacial oxide thickness, almost the same FET characteristics and electron mobility can be obtained regardless of surface treatment. We have shown that the main cause of mobility degradation is fixed-charge-induced Coulomb scattering and that phonon scattering has little effect.